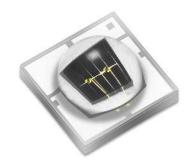


# SST-10-IRD-810nm

# **Dual Junction Surface Mount Series**

# **Low Thermal Resistance Infrared LED**



### **Table of Contents**

Technology Overview 2
Product Binning3
Ordering Information3
Optical and Electrical Characteristics
Mechanical Dimensions 8
Tape and Reel 10
Reel Information 12
Shipping information 13
Soldering14
Precautions15
Revision History 16

### **Features**

- High Power Infrared LED with typical 810nm centroid wavelength
- High thermal conductivity substrate
- 90 and 130-degree viewing angle
- Operation at up to 1.5A CW and 5A pulse
- Corrosion Robustness Class: 3B
- Built-in ESD protection
- Low Thermal Resistance
- Suitable for all SMT Assembly Methods
- RoHS and REACh compliant

## **Applications**

- Surveillance Systems / CCTV
- Iris and Face Recognition
- License Plate Scanning
- Automotive Sensing
- Machine Vision
- Night Vision





## **Technology Overview**

Luminus SST-10-IRD-810nm LEDs benefit from innovations in device technology, chip packaging and thermal management. This suite of technologies give engineers and system designers the freedom to develop solutions both high in power and efficiency.

#### Reliability

Luminus SST-10-IRD-810nm LEDs have passed a rigorous suite of environmental and mechanical stress tests, including HTOL, temperature cycling, humidity and corrosion resistance. They are fully qualified for use in a wide range of high performance and high efficacy applications.

### **REACh & RoHS Compliance**

The Luminus SST-10-IRD-810nm LED is compliant to the Restriction of Hazardous Substances Directive or RoHS. The restricted materials including lead, mercury cadmium hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ether (PBDE) are not used.

# **Understanding Luminus SST-10-IRD-810nm LED Test Specifications**

Every Luminus LED is fully tested to ensure it meets the high quality standards customers have come to expect from Luminus products.

#### **Testing Temperature**

Luminus SST-10-IRD-810nm LEDs are tested and binned at 25°C junction temperature. Temperature curves are provided to allow users to scale the data for actual operating temperature conditions.



## **Product Ordering and Shipping Part Number Nomenclature**

All SST-10-IRD-810nm products are packaged and labeled with part numbers as outlined in below. When shipped, each reel will contain only a single flux wavelength and  $V_r$  bin. The part number designation is as follows:

SST	<b>—</b> 10	— IRD	 B###	 F###-V#
<i></i>	10			1 11 11 11 V 11

Product Family Chip Area Color		Package Configuration	Bin Kit	
SST - Ceramic Surface Mount package w/ encapsulation	10: 1.0 mm²	IRD : Dual Junction Infrared	B90H: 90 deg Beam Angle B130H: 130 deg Beam Angle High Performance Ceramic 3.45mm x 3.45mm See Pages 8-9 for Detailed Drawings	See below for flux, wave- length and forward voltage binning information

#### Flux Bins<sup>1</sup>

Bin Code	Radiometric Power at 350mA, t <sub>p</sub> =20ms			
bin code	Minimum Flux (mW)	Maximum Flux (mW)		
S	475	505		
Т	505	535		
U	535	565		
V	565	595		
W	595	625		

### Wavelength Bins<sup>1</sup>

Bin Code	Minimum Peak Wavelength (nm)	Maximum Peak Wavelength (nm)
810	800	830

### Forward Voltage Bins<sup>1</sup>

Bin Code	Minimum Forward Voltage (V)	Maximum Forward Voltage (V)	
V9	2.8	3.0	
Va	3.0	3.2	
Vb	3.2	3.4	

Peak Wavelength	Minimum Flux Bin (mW)	Lens Angle	Ordering Part Number
010	475	90	SST-10-IRD-B90H-S810
810	475	130	SST-10-IRD-B130H-S810



## **Optical and Electrical Characteristics**<sup>1,5</sup>

Development	Comple of	Package Type		1124
Parameter	Symbol	B90H	B130H	Unit
Forward Current	$I_{_f}$	350		mA
Output Power Typical	PO	535		mW
Output Power at 1.0A, t = 20ms (typ.)	PO <sub>1.0A</sub>	14	70	mW
Radiant Intensity at 1.0A, t = 20ms (typ.)	$\phi_e$	770	410	mW/sr
Minimum Forward Voltage <sup>1</sup>	$V_{_{fmin}}$	2.8		V
Forward Voltage Typical	$V_{_f}$	3.0		V
Maximum Forward Voltage <sup>1</sup> $V_{fmax}$ 3.4		4	V	
Viewing Angle	2Ø <sub>1/2</sub>	90	130	deg
Peak Wavelength Typical	$\lambda_{_{P}}$	81	5	nm
Centroid Wavelength Typical	$\lambda_{c}$	810		nm
FWHM Typical Δλ <sub>1/2</sub>		3	0	nm
Temperature Coefficient of Foward Voltage	TC <sub>VF</sub>	-3.0		mV/°C
Temperature Coefficient of Radiometric Power	TC <sub>PO</sub>	-0.2		%/℃
Temperature Coefficient of Wavelength $TC_{\lambda}$		0.	3	nm/°C
Thermal Resistance (Electrical)	R <sub>th</sub>	2.	4	°C/W

Note 1: Binning based on operation at a current of 350mA, 20ms single pulse and a constant junction temperature of  $T_j = 25$ °C. Parts are binned and shipped in  $0.2VV_t$  increments.



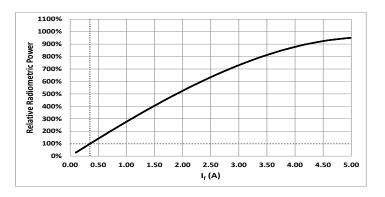
### **Absolute Maximum Ratings<sup>2</sup>**

Parameter	Symbol	Rating	Unit
Forward Current <sup>3,4</sup>	I	1.5 (CW) / 5 (Pulse)	А
Power Dissipation	P <sub>D</sub>	6	W
Reverse Voltage	V <sub>R</sub>	5	V
Storage Temperature	T <sub>stg</sub>	-40 to 100	°C
Junction Temperature <sup>3,4</sup>	T,	115°C	°C
ESD Sensitivity (HBM) - JEDEC JS-001-2014 Class 3B	V <sub>HBM</sub>	≥8000	V
	V <sub>CDM</sub>	≥1000	V

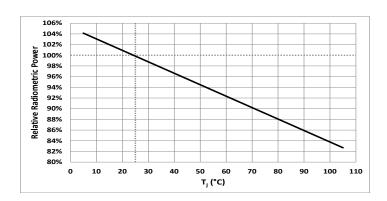
- Note 2: To prevent damage refer to operating conditions and derating curves for appropriate maximum operating conditions
- Note 3: Luminus SST-10-IRD-810nm LEDs are designed for operation up to an absolute maximum forward drive current as specified above. Product lifetime data is specified at typical forward drive currents. Sustained operation at absolute maximum currents will result in a reduction of device lifetime compared to typical forward drive currents. Actual device lifetimes will also depend on junction temperature.
- Note 4: Maximum operating case temperature combined with maximum drive current defines the total maximum operating condition for the device. To prevent damage, please operate devices within specified conditions.
- Note 5: Caution must be taken not to stare at the light emitted from these LEDs. Under special circumstances, the high intensity could damage the eye.



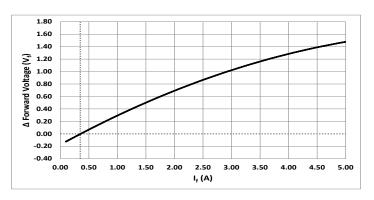
#### **Relative Output Flux vs. Forward Current**



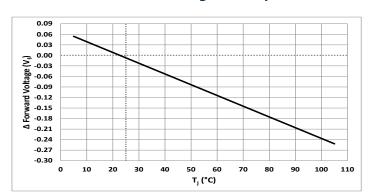
#### **Relative Output Flux vs. Temperature**



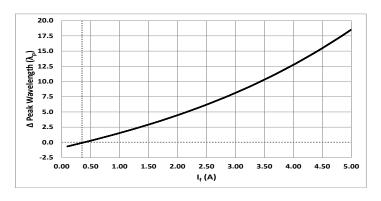
### **Relative Forward Voltage vs. Forward Current**



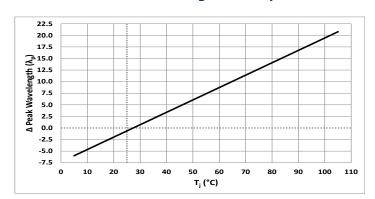
### **Relative Forward Voltage vs. Temperature**



### **Relative Peak Wavelength vs. Forward Current**

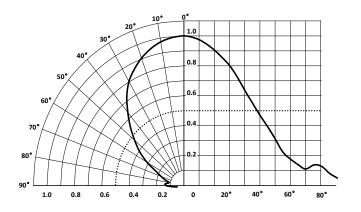


### Relative Peak Wavelength vs. Temperature

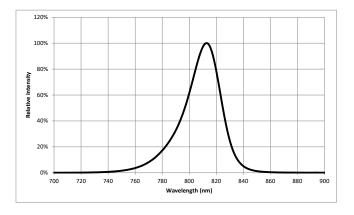




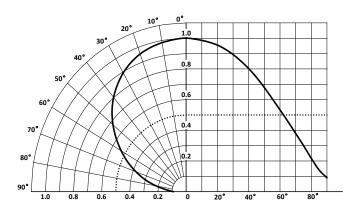
### **Typical Polar Radiation Plot - B90H**



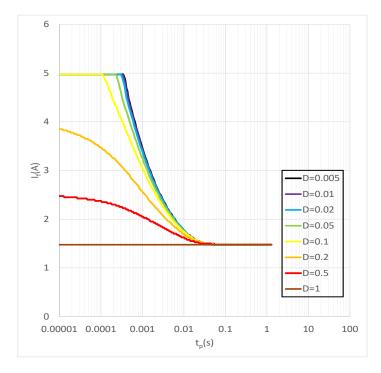
## **Typical Spectrum**



### **Typical Polar Radiation Plot - B130H**

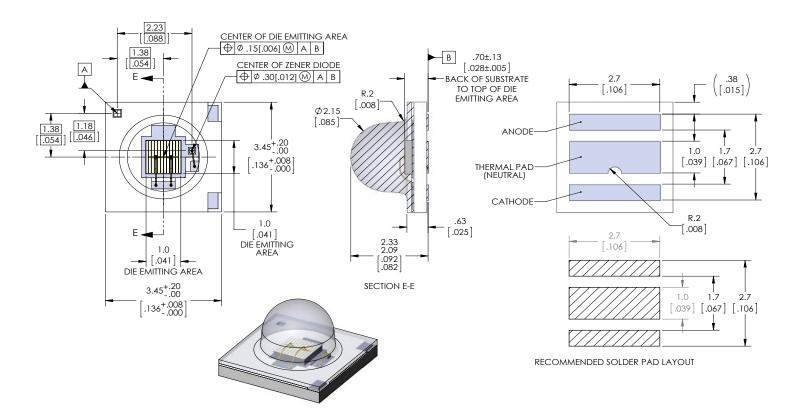


## **Permissible Pulse Handling Capability**



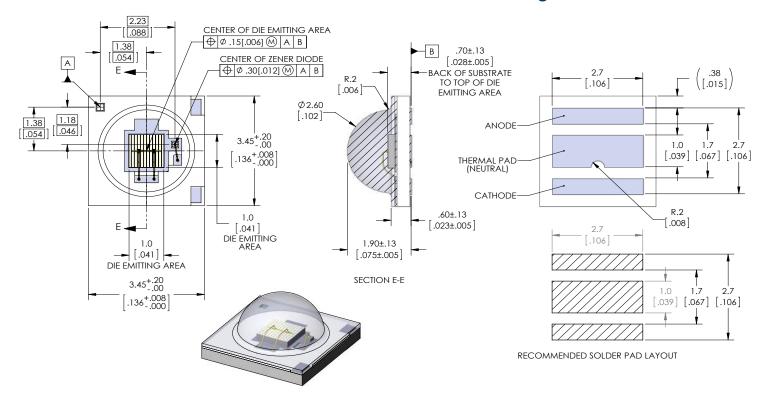


# **Mechanical Dimensions - B90H Package**



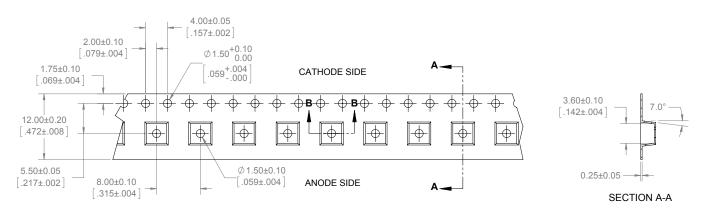


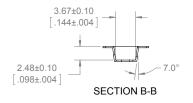
# **Mechanical Dimensions - B130H Package**





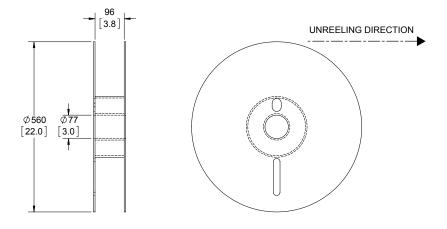
## Tape and Reel - B90H Package

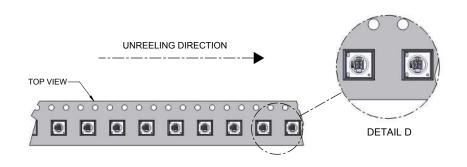




#### NOTES:

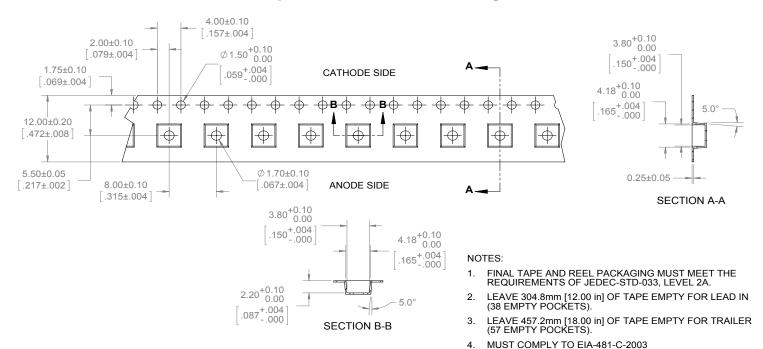
- FINAL TAPE AND REEL PACKAGING MUST MEET THE REQUIREMENTS OF JEDEC-STD-033, LEVEL 2A.
- LEAVE 304.8mm [12.00 in] OF TAPE EMPTY FOR LEAD IN (38 EMPTY POCKETS).
- 3. LEAVE 457.2mm [18.00 in] OF TAPE EMPTY FOR TRAILER (57 EMPTY POCKETS).
- 4. MUST COMPLY TO EIA-481-C-2003



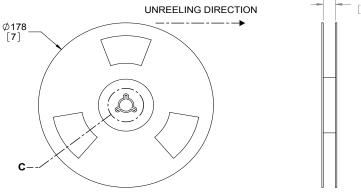


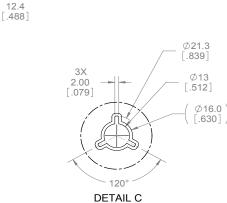


# Tape and Reel - B130H Package









UNREELING DIRECTION

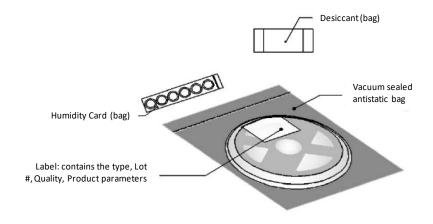
TOP VIEW

DETAIL D

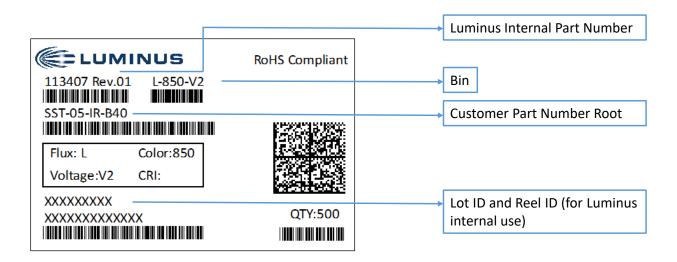


# **Reel Packaging**

## 500 parts per reel for B90H Packages - 1,000 parts per reel for B130H Package

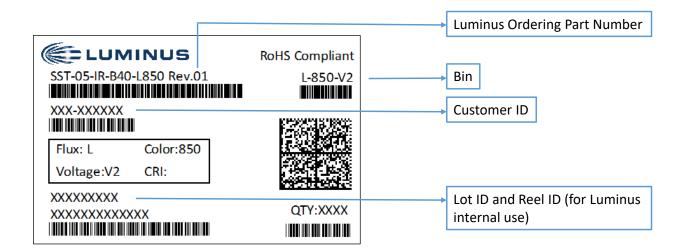


### **Reel Label**

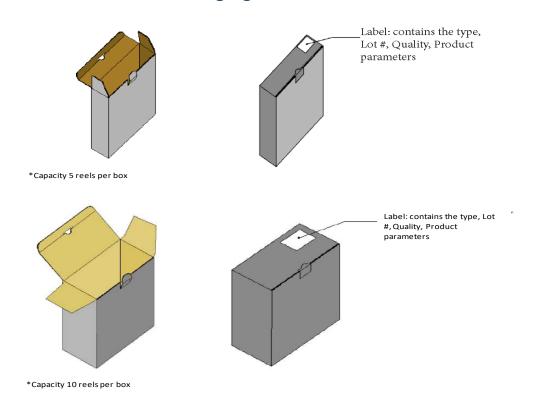




## **Shipping Label**



## **Box Packaging Information**



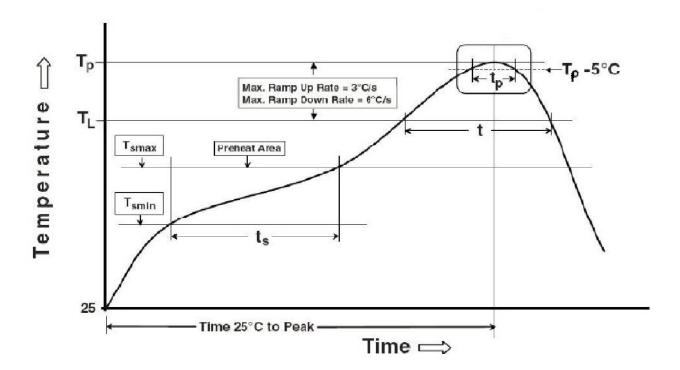


# **Soldering Profile**

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak		
Temperature min (T <sub>smin</sub> )	100°C	150°C
Temperature max (T <sub>smax</sub> )	150°C	200°C
Time $(T_{smin} \text{ to } T_{smax}) (t_s)$	60-120 seconds	60-120 seconds
Average ramp-up rate $(T_{smax} \text{ to } T_p)$	3°C/second max	3°C/second max
Liquidus temperature (T, )	183°C	217°C
Time at liquidus (t <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak temperature (T <sub>p</sub> )	235°C	260°C
Time (t <sub>p</sub> ) within 5°C of the peak tempera-	20 seconds	30 seconds
ture (Tp)		
Average ramp-down rate $(T_p \text{ to } T_{smax})$	6°C/second max	6°C/second max
Time 25°C to peak temperature	6 minutes max	8 minutes max

Note: These are general guidelines. Consult the solder paste manufacturer's datasheet for guidelines specific to the alloy and flux combination used in your application.

Product complies to MSL Level 1 according to JEDEC J-STD-020E





## **Precautions for Use**

### Storage:

### 1. Before opening the package

Unopened LEDs bags should be kept at a temperature between 15°C & 40°C and should be used within a year.

### 2. After opening the package

Opened LED moisture proof packages should be stored between 30 and 60% RH. The LEDs should be soldered within 168 hours (7days) after opening the package.

If unused LEDs remain on a reel, they should be stored in resealable moisture proof packages with new absorbent material (silica gel) and new moisture indicator cards, or better, in a dry box. If the moisture card indicates, or the first article run of the LEDs popcorns, an oven baking treatment should be performed using the following conditions: 60°C for 20 hours.

The LED electrodes and lead frames may incorporate a silver-plated copper alloy. These can be identified by a silver appearance (compared to a gold appearance). This silver surface may be affected by environmental contaminants, particularly sulfur containing compounds, during storage, and at the point of use. Please avoid conditions which may cause the LEDs to become corroded or discolored. Corrosion or discoloration can reduce solderability and/or affect optical characteristics.

Avoid rapid temperature transitions, especially in high humidity environments where condensation can occur.

### **Static Electricity:**

These products are sensitive to static electricity, and care should be taken when handling them. Static electricity or surge voltage will damage the LEDs. It is recommended to wear an anti-electrostatic wristband or anti-electrostatic gloves when handling the LEDs. All devices, equipment and machinery must be properly grounded. It is recommended that measures be taken to isolate LED processing equipment from potential sources of voltage surges.

Reference: APN-002815 Electrical Stress Damage to LEDs and How to Prevent It

#### Corrosion Resistance:

Corrosion Test: Class 3B - Test condition: 40°C / 90% RH / 15ppm H2S / 14 days (stricter than IEC60068 2-43)



## **History of Changes**

Rev	Date	Description of Change
01	05/19/2021	Initial Release

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